

**What is claimed is:**

**[Claim 1]** 1. A method for managing wafer defects comprising:  
performing an inspection step to inspect defects on each chip of each wafer and generating corresponding wafer defect raw data;  
performing a data pre-treatment step with a server to integrate the wafer defect raw data according to each chip of the same wafer and generate wafer defect distribution data for recording position, type, and size of defect;  
performing a drawing pre-treatment step with the server to generate a corresponding drawing file according to a new position, type, and size of a defect after the wafer defect distribution data is transferred integrally to display each distribution mode of each defect on the wafer on a screen; and  
performing a network management step to transmit the drawing file to a terminal without receiving the wafer defect raw data at the terminal such that a terminal user is capable of seeing the defect distributions of each chip of the wafer according to the drawing file on the drawing screen.

**[Claim 2]** 2. The method of claim 1, wherein the wafer defect raw data records a position of a wafer defect relative to a chip grid, and the data pre-treatment step transfers the position of the wafer defect to a position corresponding to the origin of the wafer to make the wafer defect distribution data record the position of the wafer defect relative to the origin.

**[Claim 3]** 3. The method of claim 1, wherein the size of the drawing file generated by the server is smaller than the sum of all wafer defect raw data corresponding to a wafer.

**[Claim 4]** 4. The method of claim 1, wherein the drawing file generated by the server is compressed, and is uncompressed by the terminal.

**[Claim 5]** 5. The method of claim 1, wherein the data pre-treatment step is according to a plurality of wafers to generate corresponding wafer defect distribution data by the server and wherein the drawing pre-treatment step is according to a plurality of wafer defect distribution data to generate a corresponding drawing file by the server.

**[Claim 6]** 6. The method of claim 5, wherein the network management step includes transmitting a plurality of drawing files to the terminal, and the terminal displaying the plurality of drawing files simultaneously on the displaying screen to present a plurality of distribution modes of wafer defects.

**[Claim 7]** 7. The method of claim 1, wherein the wafer defect raw data records a position of a wafer defect relative to a chip grid, the inspection step performs defect inspection in at least two different inspection stations in sequence to generate the corresponding wafer defect raw data, and the data pre-treatment step further comprises subtracting a defect position recorded by the wafer defect raw data of a prior wafer inspection station from the wafer defect raw data corresponding to a given wafer inspection station to generate the data of a new defect in the wafer inspection station and record the data of the new defect in the wafer defect distribution data.